BGA Heat Sink - High Performance ASIC Cooling





ATS Part#: ATS-56011-C1-R0

Description: 57.50 x 57.50 x 12.50 mm BGA Heat Sink - High Performance ASIC Cooling

Heat Sink Type: ASIC Cooling
Heat Sink Attachment: Thermal Tape
Equivalent Part Number: ATS-56011-C3-R0

*Image above is for illustration purpose only.

Features & Benefits

- maxiFLOW™ design features a low profile, spread fin array that maximizes surface area for more effective convection (air) cooling
- · Designed specifically for ASIC package and their unique cooling requirements
- · Comes preassembled with high performance thermal interface material

Thermal Performance

AIR VELOCITY		@200 LFM 1.0 M/S	@300 LFM 1.5 M/S	@400 LFM 2.0 M/S	@500 LFM 2.5 M/S	@600 LFM 3.0 M/S	@700 LFM 3.5 M/S	@800 LFM 4.0 M/S
THERMAL RESISTANCE	Unducted Flow	2.3 °C/W	1.8 °C/W	1.3 °C/W	1.2 °C/W	1 °C/W	0.8 °C/W	0.7 °C/W
	Ducted Flow	1.1	N/A	N/A	N/A	N/A	N/A	N/A

Product Detail

Schematic Image	Dimension A	Dimension B	Dimension C	Dimension D	TIM	Finish			
	57.50 mm	57.50 mm	12.50 mm	70 mm	T412	BLACK-ANODIZED			
	 Notes: Dimension A and B refer to component size. Dimension C is the heat sink height from the bottom of the base to the top of the fin field. ATS-56011-C3-R0 is the exact heat sink assembly with an equivalent thermal interface material (Saint-Gobain C675). Thermal performance data are provided for reference only. Actual performance may vary by application. ATS reserves the right to update or change its products without notice to improve the design or performance. ATS certifies that this heat sink assembly is RoHS-6 and REACH compliant. Contact ATS to learn about custom options available. 								
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